

Appn No. 10/791,840  
Amdt. Dated July 18, 2005  
Response to Office action of April 20, 2005

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**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A method including :
  - a) providing a wafer having a plurality of microfabricated devices devices and a plurality of bond pads formed thereon;
  - b) applying a plurality of substantially hollow caps to a first side of the wafer, the caps positioned such that, in plan view, each cap overlays part or all of at least one microfabricated device and such that said bond pads are exposed;
  - c) applying a plurality of substantially hollow caps to a second side of the wafer, the caps positioned such that, in plan view, the caps provide a mask to said bond pads; and
  - ed) applying one or more etches to the wafer from the first-second side toward the other first side to etch away at least some of the material between the peripheries of said caps to separate the wafer into separate units.
2. (Original) The method of claim 1 wherein each cap is joined to any adjacent cap by a thin layer of material extending between the periphery of each of the caps.
3. (Original) The method of claim 2 wherein the one or more etches are applied such that the layer of material adjoining adjacent caps is removed.
4. (Original) The method of claim 3 wherein the layer of material adjoining adjacent caps is removed by an oxygen etch.
5. (Cancelled).
6. (Currently Amended) The method of claim 1 wherein a first plurality of caps are applied to the bottom side of the wafer and a second plurality of caps are applied to the top side of the wafer, and wherein in plan view, each of the second-first plurality of caps overlays all or part of one or more microfabricated devices; and, in plan view, each of the first-second plurality of caps cover the corresponding second-first cap.